PUBLICATION No.

Reference

Messrs. Digi-key

EMI FILTER Specification

Part No. :KNH21 Series

RoHS Compliant

<u>19.Aug., 2011</u>

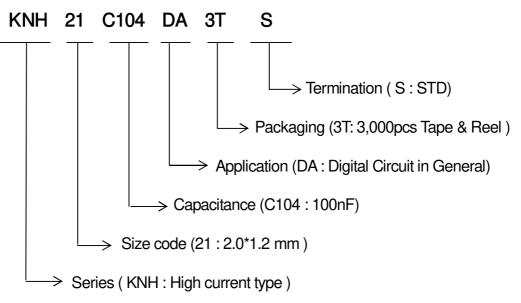
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EMI FILTER SPECIFICATION

1. Apply

This specification applies to Kyocera chip EMI filter KNH21 Series.

2. Nomenclature

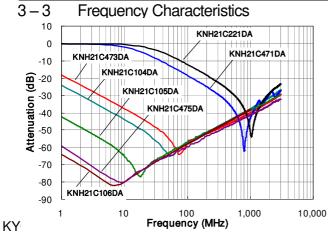


3. Performance / Requirement

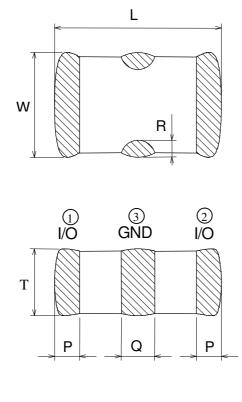
3–1	Standard requirement	
	A: Insulation resistance	Min. 500 (M ohm)
	B: Operating temperature	-40 to 85 (deg.)

3–2 Electrical characteristics

	Capacitance	Rated	Rated	Direct - current
Parts Number	(+50 / -20 %)	current	voltage	resistance
	(pF)	(A)	(V)	(Ohm)
KNH21C221DA3TS	220	1.0	50	Max. 0.08
KNH21C471DA3TS	470	1.0	50	Max. 0.08
KNH21C473DA3TS	47,000	2.0	50	Max. 0.02
KNH21C104DA3TS	100,000	2.0	25	Max. 0.02
KNH21C105DA3TS	1,000,000	4.0	10	Max. 0.02
KNH21C475DA3TS	4,700,000	4.0	6.3	Max. 0.02
KNH21C106DA3TS	10,000,000	6.0	6.3	Max. 0.01



4. Size and dimensions



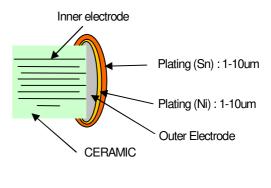
(Figure -1)

Unit : mm

Dimensions
2.00 + / - 0.20
1.25 + / - 0.20
0.85 + / - 0.15 *1
0.30 + / - 0.20
0.40 + / - 0.20
Min. 0.01

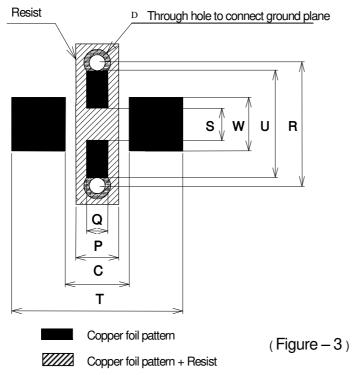
*1 KNH21C475DA: 1.0+- 0.15

*1 KNH21C106DA: 1.0+- 0.15



(Figure - 2)

5. Recommended land pattern



	Unit : mm
Symbol	Dimensions
Т	3.20
W	1.00
R	2.30
С	1.20
Р	0.80
Q	0.40
S	0.60
U	2.00
D	0.3 to 0.4

6. Requirement and measurement method

No	Contents	Requirement	Measurement method and conditions
1	Appearance	No serious defect.	Microscope (10 magnifications).
2	Dimensions	Figure – 1	Digital caliper and measurement microscope.
3	Capacitance	3 – 2 item	Measured by HP4278A. Capaci Measured Measured -tance frequency voltage 22pF to 1MHz 470pF +- 10kHz 1V+- 0.2V 47nF to 1kHz rms 10uF +-10Hz
4	Insulation resistance	3 – 1 item	Measured by super meg ohmmeter model SM – 9E (made by TOA). 1-3 or 2-3 (at figure – 1) measured. To measure after charging with the rated voltage for 1 minute at room temperature and normal humidity.
5	Dielectric strength	No problem observed.	To charge between $1 (\text{ or } 3)$ and $2 $ (at figure – 1) with the 2.5 times high of the rated voltage for 1 to 5 seconds.
6	Current resistance	No problem observed.	Print rated current for 1 to 5 seconds between 1-2 (at figure – 1).
7	Solderability	Coverage Min. 90 % Each termination.	Completely coat parts with flux and propanol solution and preheat for 1 minute at 120 to 150deg Afterwards, dip parts into solder bath for 2+-0.5 seconds at 230+-5deg Solder level checked by naked eye under microscope.

No	Contents	Requirement	Measurement method and conditions	
8	Soldering heat resistance	No mechanical defect. I.R. ; Min. 500M ohms Capacitance variation ;+-20%	Completely coat parts with flux and propanol solution and preheat for 1 minute at 120 to 150deg Afterwards, dip parts into solder bath for 10+-1 seconds at 260+-5deg Measure after 24+-2 hours.	
9	Bending strength test	No mechanical defect.	As shown below glass epoxy board (t=1.6mm) is soldered. Mechanical pressure is applied and bent 1 mm for 3 seconds. R340 $R340$ $1.0 mm$ $45 mm$ $45 mm$ $(Figure - 4)$	
10	Temperature cycle	No mechanical defect. I.R. ; Min. 500M ohms Capacitance variation ; +- 30%	As specified bellow, the steps are repeated 10 cycles. Temperature Time (deg.) (Minutes) 1 -25+-3 30+-3 2 Room Temp. 2 to 5 3 85+-2 30+-3 4 Room Temp. 2 to 5 Measure after 24+-2 hours.	
11	Humidity test	No mechanical defect. I.R. ; Min. 500M ohm Capacitance variation ; +- 30%	Leave at 40+-2deg.,humidity 90 to 95%Rh atmosphere for 500+-12 hours. Measure after 24+-2 hours.	
12	High temperature with loading	No mechanical defect. I.R. ; Min. 500Mohm Capacitance variation ; +- 30%	Loading rated direct – current voltage continuously under 85+-3 deg. environment for 500+-12 hours. Measure after 24+-2 hours.	

7. Outgoing quality standards

Standard	AQL(%)		
S-1	2.5		
I	1		
S-4	1		
S-4	1		
S-4	1		
	Standard S-1 I S-4 S-4		

Randomly inspected by ANSi – ASQC Z 1.4

8. Recommended storage conditions

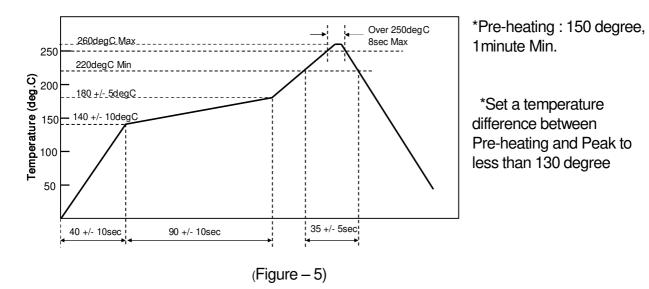
Temperature	;	-10 to 45 deg.
Humidity	:	45 to 75 %RH

9. Product site

KYOCERA Corporation Kagoshima Kokubu plant Japan

10. Standard soldering conditions

[Reflow soldering condition]



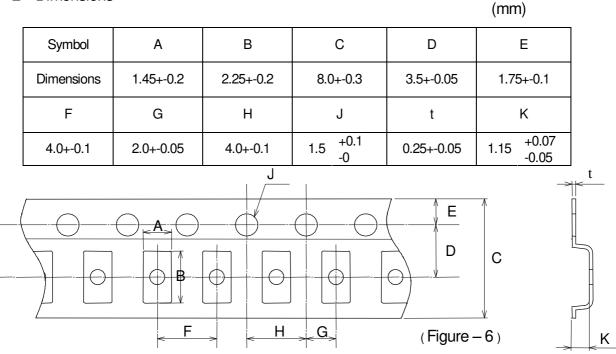
Taping packaging specification

1) Apply

This specification applies to Kyocera chip EMI filter [KNH21 series] taping.

2) Tape

- 2 1Material Plastic
- 2 2Dimensions

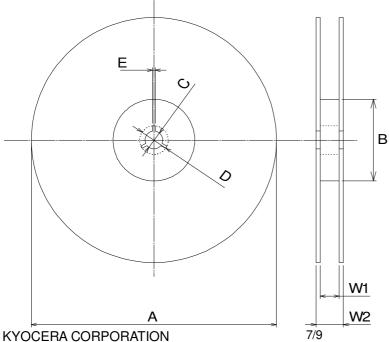


3) Taping configuration

3-1 Unit by reel

Taping for 1 reel is 3,000 pcs STD. Also, components should be placed in consecutively without any vacancy.

3-2 Reel dimensions



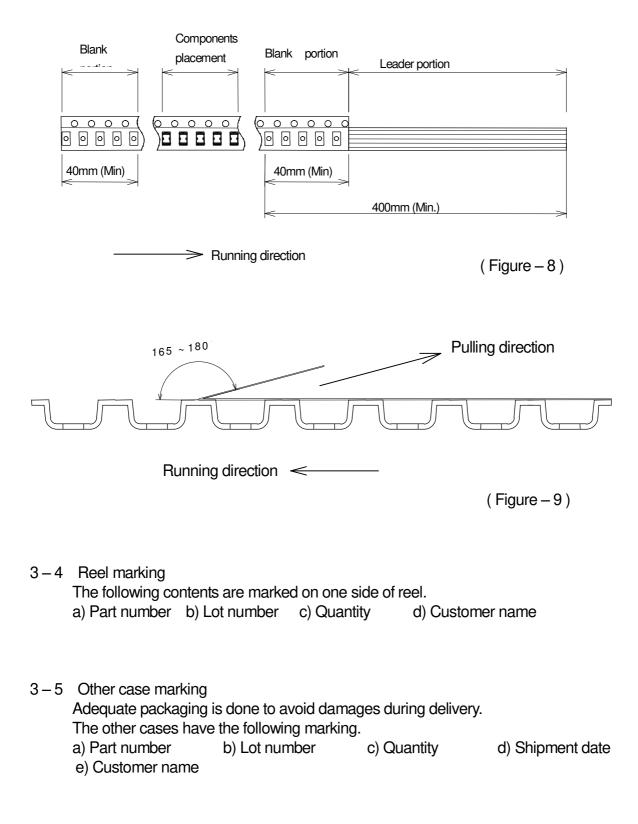
Symbol	Dimensions
А	d180 ⁺⁰ -3.0
В	D60 +1.0 -0
С	d13 +/- 0.5
D	d21 +/- 0.8
E	2.0 +/- 0.5
W1	9.3 ⁺⁰ -0.15
W2	11.4± 1.0

No.EE21-KHDC000-02

3-3 Leader portion and blank portion

(Figure - 9)

As shown in drawing 8, there is space for leader portion and blank portion. Furthermore, the pulling strength of carrier tape and top tape is 45 + 35 g as shown in drawing 9.



Limitation of use

Make sure to contact us in advance before considering using this product for the following applications which would require particularly high reliability due to possibility of direct harm to lives and/or properties.

- (1)Use in aerospace or space
- (2)Use in seabed or underground
- (3)Use in control of power station firepower, waterpower, nuclearpower, etc
- (4)Use in medical treatments including instruments related to lifesaver
- (5)Use in transportation cars, trains, ships, etc.
- (6)Use in traffic controls
- (7)Use in protection/prevention against disasters or crimes
- (8)Use in information processing
- (9)Others Use in the equivalent applications mentioned above

This product is designed and manufactured with intention to be used in general electronic equipments for standard applications but with no intention to be used in the following environments which may affect performance of this product. Therefore, make sure to have enough confirmation on performance and reliability of this product in the following environments in advance before use.

(1)Use in liquids such as water, oil, medical liquid, organic solvent, etc

- (2)Use in direct sunshine, rain, wind, or dust/dirt
- (3)Use in sea wind or place with corrosive gas such as Cl2, H2S, NH3, SO2, NO2, etc
- (4)Use in environment with strong static electricity or electromagnetic wave
- (5)Use in located nearly to heat generating part or flammable materials such as vinyl wires (6)Use in condensation
- (7)Use in sealed or coated by materials such as resin, etc